TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	IC PACKAGE HAVING GROUND IC CHIP AND METHOD OF MANUFACTURING SAME

Application Number :	
Date :	
First Named Applicant:	PEI-HAW TSAO
Confirmation Number:	
Attorney Docket Number:	TSMC2003-1622

Submitted By:	Elec. Sign.	Sign. Capacity
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Documents being submitted:	Files
us-assignment	TSMC1622-usassn.xml
	us-assignment.xsl
	us-assignment.dtd
	1622assg_1.tif
	1622assg_2.tif
	1622assg_3.tif
	1622assg_4.tif
us-request	TSMC1622-usrequ.xml
	us-request.dtd
	us-request.xsl
us-declaration	TSMC1622-usdecl.xml
	us-declaration.dtd
	us-declaration.xsl
us-fee-sheet	TSMC1622-usfees.xml
	us-fee-sheet.xsl
	us-fee-sheet.dtd
us-ids	TSMC1622-usidst.xml
	us-ids.dtd
	us-ids.xsl
us-power-of-attorney-grant	TSMC1622-uspoat.xml
	us-power-of-attorney-grant.dtd
	us-power-of-attorney-grant.xsl
application-body	2003-1622.xml
	application-body.dtd
	Image1.tif
	Image2.tif
	isoamsa.ent
	isoamsb.ent
	isoamsc.ent
	isoamsn.ent
	isoamso.ent
	isoamsr.ent
	isobox.ent
	isocyr1.ent
	isocyr2.ent
	isodia.ent
	isogrk1.ent
	isogrk2.ent
	isogrk3.ent
	isogrk4.ent
	isolat1.ent
	isolat2.ent
	isomfrk.ent
	isomopf.ent
	isomscr.ent
	isonum.ent
	isopub.ent
	isotech.ent
	mathml2.dtd

	mathml2-qname-1.mod
	mmlalias.ent
	mmlextra.ent
	soextblx.dtd
	us-application-body.xsl
	wipo.ent
application-body-pdf-wrap	2003-1622-pdf-wrap.xml
abstract-pdf	2003-1622-abst.pdf
claims-pdf	2003-1622-clms.pdf
description-pdf	2003-1622-desc.pdf
drawings-pdf	2003-1622-draw.pdf

Comments